

EXPLOSIVE CRYSTALLIZATION OF RF-SPUTTERED
AMORPHOUS CdTe FILMS

S.V. Krishnaswamy, R. Messier, P. Swab, L.L. Tongson
and K. Vedam

Materials Research Laboratory

The Pennsylvania State University
University Park, PA 16802

(Received July 18, 1980; revised November 3, 1980)

Explosive crystallization of about 2- μm thick amorphous CdTe films prepared by rf-sputtering in an Ar-N₂ ambient has been observed. The transformation can be initiated with or without external thermal or mechanical impulses depending on the oxygen content of the films. The crystallization is accompanied by a light flash. X-ray diffraction, Auger analysis, and resistivity measurements were made on these films to arrive at a qualitative model to explain the observations.

Key words: explosive crystallization, amorphous semiconductors, rf-sputtered films.

Introduction

"Explosive" amorphous-to-crystalline transformations in sputter-deposited amorphous Ge films were first reported by Messier et al. [1-6] Their study of the phenomenon occurring at room temperature showed that the transformation is highly exothermic and that the crystallization of the entire sample occurs by a series of "microexplosions," in which both an initiation and a propagation mechanism were identified. The crystallization could be initiated by any localized energy impulse such as (i) laser pulsing or e-beam; (ii) touching

with a heated glass tip or microtorch (thermal); or (iii) pricking with a sharp point (mechanical). The propagation velocity is reported to be on the order of 120 cm/sec and in this process an estimated bulk temperature of 500°C is reached. [4] Explosive crystallization could be quenched by lowering the sample temperature to 78 K. Their results were later confirmed by Kikuchi et al. [7,8]

Wickersham et al. [9] reported a similar observation on what they termed "impulse-stimulated crystallization" in sputter-deposited amorphous (In,Ga)Sb films. Their results indicate that a minimum temperature T^* is needed for micro-explosions to propagate and that T^* depends on the film composition as well as the thermal annealing history of the film. Further, T^* was observed to be above room temperature with T^* increasing for higher pre-annealing temperatures and longer pre-annealing times. The propagation velocity of the transformation was on the order of 200 cm/sec. The explosive crystallization in these alloys was always found to be associated with large changes in sample resistivity and reflectivity.

Based upon the work in the above studies, Fan et al. [10] showed that by more precisely controlling the propagation of laser-initiated explosive crystallization, through regulation of both film temperature and laser power density, very large crystallite-sized Ge films could be prepared. Thus the potential exists for obtaining large crystallite-size, or even single crystal, films of Ge and other semiconductors on inexpensive, large area substrates.

In this paper we report the preparation of a particular set of noncrystalline (or amorphous) CdTe films prepared in an Ar/N₂ sputtering gas atmosphere, hereafter designated as a-CdTe:N, which also show this explosive crystallization phenomenon. The crystallization occurred spontaneously during initial exposure to ambient conditions in our earlier experiments but subsequently could be controlled and stimulated externally by both mechanical as well as thermal means.

Experimental

Films were sputtered from a 5" dia hot pressed target (99.99% purity) using an MRC rf-sputtering system with a residual background pressure $\sim 10^{-7}$ torr. A mixture of

purified Ar at 20×10^{-3} torr pressure and Linde UHP grade N₂ (purity quoted by manufacturer was 99.999% with oxygen < 1 ppm and moisture < 3 ppm) at a flow rate of 20 std cc/min (~ 4 to 5×10^{-3} torr) was employed. The substrate-to-target distance was fixed at 40 mm, and the rf-power density was maintained at 0.4 watts/cm² in obtaining the 2- μ m thick films. Ultrasonically cleaned glass slides (Fisher 12-549) and fused silica cover slips were used as substrates. No substrate heating or cooling was employed. However, in the steady state, substrate temperatures $T_S \sim 80$ -100°C were recorded, as measured by a thermally aged and calibrated noncrystalline Ge thermistor-type film, agreeing with the observation by Gilbert et al. [15] After deposition the films were usually kept under vacuum for several hours allowing T_S to come to room temperature before removal from the system. However, on breaking the vacuum and on removal from the vacuum chamber the films appeared grayish and the substrate platform was unusually warm. Even a cursory inspection of these CdTe:N films revealed features characteristic of explosively crystallized (EC) a-Ge films. The spontaneous crystallization of these a-CdTe:N films had evidently occurred during exposure to the atmosphere, and further it was found that they were highly reproducible and independent of the gas leaked into the vacuum chamber for their removal. This behavior, however, was not observed for a-CdTe films prepared by sputtering in a pure Ar atmosphere. This transformation, while the sample is inside the chamber (in-situ explosive crystallization--IEC), should be distinguished from the a-Ge and a-(In,Ga)Sb cases in which crystallization was achieved only by external triggering (ex-situ explosive crystallization--EEC). Further, the as-sputtered noncrystalline films changed from a translucent, reddish-yellow to gray upon transformation.

Results and Discussion

It was found that even trace levels (ppm range) of oxygen impurities in the gas stabilized the films so that they could be removed from the chamber without spontaneous crystallization. Once such a film is taken out of the vacuum system, EEC could be initiated by any means similar to that for the case of explosive Ge. By carefully controlling the oxygen content in the sputtering chamber during sputtering, even more stable films that would not transform at room temperature could be prepared. However, on raising

the temperature of such samples to 80°C and simultaneously applying a mechanical impulse, the films could be made to explosively crystallize. The critical temperature T^* thus seems to depend on the partial pressure of oxygen during preparation. Increasing oxygen content well beyond trace level completely stabilized the film to a point that no EC could be triggered. Further, even the partially stable films that would otherwise have exploded at room temperature on mere mechanical contact, tended to stabilize on exposure to air over a period of time. The longer they were exposed the more stable they became indicating a metastability decrease induced by postdeposition oxidation. When these partially stable films were immersed in water or liquid nitrogen no EC could be generated.

In addition to a change in color, both IEC and EEC were accompanied by a flash of light (estimated in the milli-second duration range) with sufficient intensity, and thereby enabling us to photograph the inside of our sputtering chamber without any additional illumination. Figure 1

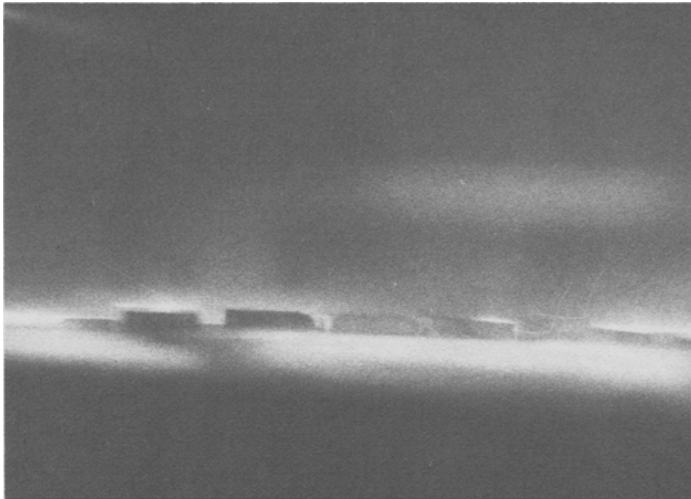


Fig. 1. A photograph showing the substrates placed on the platform inside vacuum chamber. This picture was taken with the camera wide open and using only the light flash from explosive crystallization and no other light source.

shows such a picture taken with a Pentax ($f/1.4$ lens) camera using high speed recording film, Kodak RE-135 (1600 ASA). The picture shows four fused silica substrates (9 mm x 9 mm) arranged on a platform. Our preliminary attempts at spectrographic characterization of the flash were not successful. A more systematic attempt is planned for the future. Further, for EEC a black "smoke" followed the flash.

In order to study the effect of the substrate, films were deposited on various substrates (e.g., fused silica, Mo, glass, stainless steel, Au, Cu, and Al) covering a wide range of thermal expansion and thermal conductivity. All films regardless of substrate, exhibited both in-situ as well as ex-situ crystallization depending on the oxygen content. Finally, the electrical resistivity ρ was measured with sputtered Ni contacts on the films. While resistivity for a-CdTe was $\sim 10^6 \Omega\text{-cm}$, EC films were $\sim 40 \Omega\text{-cm}$, lower by more than 5 orders of magnitude. Wickersham et al. [9] reported a similar observation with their (In,Ga)Sb films, although the resistivity dropped only by 3 orders of magnitude in their experiments.

X-ray diffraction patterns (Fig. 2a) of non-transformed films revealed its amorphous nature, while explosively crystallized films showed sharp diffraction peaks corresponding to both sphalerite and wurtzite (cubic and hexagonal, respectively) phases of CdTe. Figure 3 is an SEM micrograph of an EEC CdTe:N film, the surface of which appears generally covered with crystallites on the order of $0.1 \mu\text{m}$ and agglomerates on the order of $1 \mu\text{m}$. Near the sites of EC initiation, however, agglomerates nearly ten times larger are found. Another sample which appeared less grayish to the eye also had $0.5 \mu\text{m}$ agglomerates but fewer in number. When the agglomerates are on the order of the wavelength of light and closely spaced, the surface has a graded refractive index leading to high light absorption. Such light scattering results in the grayish appearance.

Auger Electron Spectrometry (AES) was used to determine the chemical compositions of several amorphous (i.e., unexploded), IEC, and ECC films, and typical results are given in Table 1. In addition, Auger scans were carried out on the materials which were ejected during an ex-situ explosion and collected on a nearby copper substrate. The Auger spectra in the derivative mode were recorded using a 1.5 keV, 20 μA

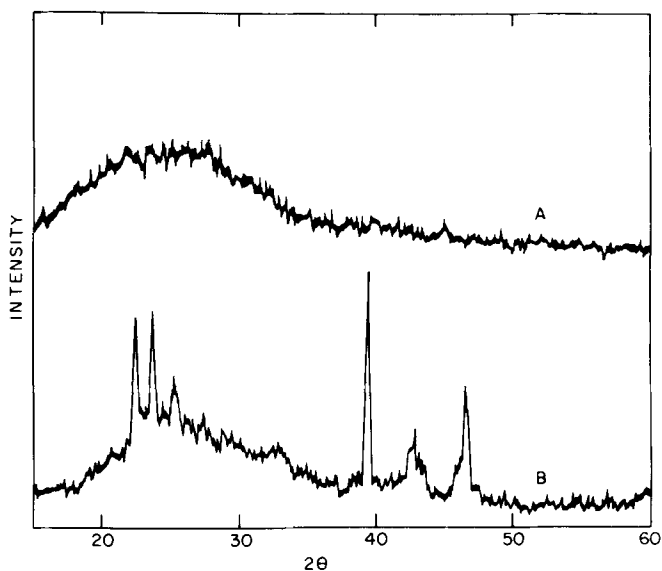


Fig. 2. X-ray diffraction pattern of (a) as-deposited CdTe film on fused silica substrate showing amorphous nature, and (b) explosively crystallized film revealing various diffraction peaks.

Table I. Nature and Composition of Representative Films

Sample #	Nature	AES Atomic Concentration			N ₂ Purity
		Cd	Te	O	
KO20	IEC (highly unstable)	41	58	1	*
KO19	Exploded film collected on to Cu foil	34	64	2	**
		37	61	2	**
KO16	EEC (partially stable)	41	54	5	**
KO17	Stable amorphous film (crystallized only above 80°C)	49	37	14	**

* Ultra-high purity (99.999% with < 1 ppm O₂)

** High purity (99.99% with > 3 ppm O₂)

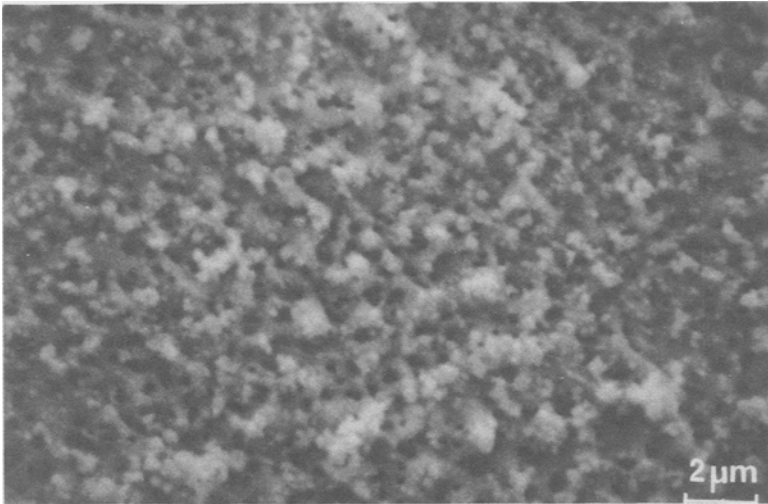


Fig. 3. SEM photograph of top surface of an explosively crystallized film.

primary electron beam. Surface composition was evaluated from the Auger data using Eq. (8) of Ref. 16

$$C_x = \left(\frac{I_x/k_x}{\sum_i I_i/k_i} \right) \quad (1)$$

where I_x is the Auger peak-to-peak signal, C_x is the concentration of element X, k_x is the sensitivity of X relative to an arbitrary standard, and the summation is over all the elements present. In this study, the Cd-376 eV, Te-483 eV and 0-512 eV Auger peaks were used. Auger sensitivities for O and Te relative to Cd were evaluated from MgO, Te and Cd standards as in Ref. 16. The applicability of Eq. (1) was demonstrated recently by Tongson et al. [17] in determining the composition of densified WC-Co composite material.

A careful analysis of Auger data gave no conclusive indication of the presence of nitrogen in the films. A drawback of AES for the CdTe:N system is that the Cd-382 eV peak interferes with the KLL transition of N at 381 eV. However, the presence of N may be inferred by comparing the Cd 382/Cd 376 ratio obtained from the films with the corresponding

ratio from elemental Cd. In our case these two ratios agreed to within experimental error.

Table I shows typical Cd, Te and O concentrations as a function of the nature (i.e., amorphous, IEC, ECC) of the films and the ambient conditions during deposition. The precision of the normalized concentrations is better than 1%. From Table I it appears that the IEC films contained the smallest amount of oxygen and stable amorphous films contain a larger fraction of oxygen, possibly incorporated as CdO. During explosion CdO may dissociate, resulting in a lower oxygen content in the collected deposit.

The above observations can be explained by an extension of the model proposed for a-Ge. [2,4,5] This crystallization phenomenon consists of two distinct mechanisms, an initiation and a propagation mechanism. The initiation is controlled primarily by the metastable state of the noncrystalline films, while the propagation is controlled not only by this structural metastability (and the net energy gain during transformation on an atomic scale), but also by the efficiency of transfer of this energy from atom-to-atom on times $\sim 10^{-10}$ sec. The observation that a continuous range in a-CdTe:N film metastability is found (as manifested in its crystallization behavior) and understood in terms of oxygen stabilization then gives us a clue as to the initiation mechanism.

The as-deposited, amorphous CdTe:N films are in a highly metastable state requiring a relatively small activation energy for transformation to the crystalline state as compared to the net energy gained during the crystallization. It is not uncommon that thin films undergo a change in stress state upon exposure to air. For instance, Paesler [18] has observed a reduction in tensile stress on exposing freshly evaporated a-Ge films to moist air and attributes this to water adsorption or oxidation. Recently, Tsai and Fritsche [19] have shown that a-Si films adsorb 6.5 mol% water within 1 min after air exposure and 12 mol% after 16 hrs and attribute the behavior to the well-documented void network structure in such materials.

The proposed explanation then follows. Upon initial air or controlled atmosphere exposure, gases or water vapor are physisorbed on all surfaces (including internal voids originating at the film surface) causing a change in the stress state particularly over a thin top layer of the film. When

the film has a low oxygen content, a sufficiently high metastable state exists such that this stress change initiates the IEC behavior. As various films are prepared with higher, controlled oxygen contents this metastability decreases to the point that this atmosphere-exposure induced stress change is not sufficient to initiate EC. This marks the change between IEC and ECC behavior. If any small, localized mechanical stress is immediately applied, EEC occurs. However, if the application of this mechanical stress is delayed after air-exposure, a larger amount of external force is required to initiate EC, the necessary force increasing with exposure time. Thus postdeposition oxidation appears to be continually stabilizing the initially highly metastable films. In fact, after approximately a one-day exposure to air the EC could no longer be initiated.

In this connection, the recent study by Kennealy et al. [22] on chemiexcitation between metastable atomic nitrogen and molecular oxygen which is also a largely exothermic reaction, is relevant. They find that the observed IR radiation corresponds to an N-O vibrational spectra created solely by the chemical reaction, unaffected by any relaxation process. It is interesting to note that they compute the energy released to be anywhere from 1 to 4 eV depending on the reaction path. Such a mechanism could account for both the explosive crystallization of CdTe:N films and the accompanying light flash.

In summary, we have prepared CdTe:N films that explosively crystallize, the explosive nature of which is dependent on the preparation history, in particular the oxygen content in the ambient as well as the post-oxidation treatment. While the phenomenon is similar to that observed in a-Ge films, the striking feature is that it takes place for much thinner films-EC in Ge needed $\sim 20\text{-}\mu\text{m}$ whereas EC in CdTe:N is possible in a $2\text{-}\mu\text{m}$ thick film. Further, the extent of crystallization is also large compared with a-Ge. A more detailed study relating this phenomenon to the film microstructure and nanostructure will be reported elsewhere.

Acknowledgment

The authors wish to thank National Patent Development Corporation for partial support of this research.

References

- (1) T. Takamori, R. Messier and R. Roy, Appl. Phys. Lett. 20, 201 (1972).
- (2) R. Messier, T. Takamori and R. Roy, J. Non-Cryst. Solids 8-10, 816 (1972).
- (3) T. Takamori, R. Messier and R. Roy, J. Mat. Sci. 8, 1809 (1973).
- (4) R. Messier, T. Takamori and R. Roy, Solid State Commun. 16, 311 (1975).
- (5) R. Messier, Ph.D. Thesis, The Pennsylvania State University (March 1973), unpublished.
- (6) T. Takamori, R. Messier and R. Roy, J. Mat. Sci. 9, 159 (1974).
- (7) A. Mineo, A. Matsuda, T. Kurosu and M. Kikuchi, Solid State Commun. 13, 329 (1973).
- (8) M. Kikuchi, A. Matsuda, T. Kurosu, A. Mineo and K. J. Callanhan, Solid State Commun. 14 713 (1974).
- (9) C. E. Wickersham, G. Bajor and J. E. Greene, Solid State Commun. 27 17 (1978).
- (10) J. C. Fan, H. J. Zeiger, R. P. Gale and R. L. Chapman, Appl. Phys. Lett. 36, 158 (1980).
- (11) G. H. Gilmer and H. J. Leamy, Abstracts, Annual Meeting of the Materials Research Society, Boston, MA, 1979, unpublished.
- (12) R. B. Gold, J. G. Gibbons, T. J. Magee, J. Peng and R. Osmond, Abstracts, Annual Meeting of the Materials Research Society, Boston, MA, 1979, unpublished.
- (13) R. B. Gold and J. F. Gibbons, Abstracts, 21st Electronic Materials Conference, Boulder, CO, June 1979, unpublished.
- (14) J. C. C. Fan, R. L. Chapman, R. P. Gale, H. J. Zeiger, Abstracts, 21st Electronic Materials Conference, Boulder, CO, June 1979, unpublished.

- (15) L. R. Gilbert, L. L. Tongson and R. Roy, unpublished.
- (16) L. E. Davis, N. C. MacDonald, P. W. Palmberg, G. E. Riach and R. E. Weber, Handbook of Auger Electron Spectroscopy, Physical Electronics, Edina, NY (1976), 2nd Ed.
- (17) L. L. Tongson, J. V. Biggers, G. O. Dayton, J. M. Bind and B. E. Knox, J. Vac. Sci. Tech. 15, 1133 (1978).
- (18) M. A. Paesler, in Amorphous and Liquid Semiconductors, eds. J. Stuke and W. Brenig, Taylor-Francis, Ltd., London, 1974, p. 229.
- (19) C. C. Tsai and H. Fritsche, Bull. Am. Phys. Soc. 24 (3), 399 (1979).
- (20) See for example, A. Barna, P. B. Barna, G. Radnoczi, H. Sugawara and P. Thomas, Thin Solid Films 48, 163 (1978).
- (21) S. V. Krishnaswamy, R. Messier, Yee S. Ng., T. T. Tsong and S. B. McLane, J. Non-Cryst. Solids 35 36, 531 (1980).
- (22) J. P. Kennealy and F. P. Del Greco, J. Chem. Phys. 69, 1574 (1978).